

Immersion Gold SLOGOLD 10

Immersion Gold SLOGOLD 10 has been developed in order to plate a 24 carat gold layer on electroless deposited nickel layers by simple electroless dipping.

Gold deposition is due to metal exchange in which bondable gold coatings with a thickness of up to max. 0.1 µm can be achieved. The degree of brightness is equivalent to the brightness of the base material.

Immersion Gold SLOGOLD 10 is applied if electrolytic processes fail due to their restricted covering power or e.g. in the PCB technology so called ENIG layers (Electroless Nickel - Immersion Gold) should be deposited.

The information in this data sheet is based on laboratory as well as practical experience. Figures quoted for operating limits and replenishment quantities are for guidance only. Actual values necessary will depend on the components being plated (material and geometry), their application and plating plant conditions.

Important:

Please read this instructions carefully prior to the use of the process and carefully follow all the parameters that have a direct influence on the operation. We reserve the right to make technical changes. In the interest of safety, please pay attention to the hazard warnings on the labels of the containers. The minimum shelf life of the products is included on the labels and is also available in the appropriate Quality Assurance (QA03).

The current IMDS number of the layer deposited from the process is available on the internet at www.schloetter.com/downloads.

For the storage of chemical products the TRGS 510 must be followed.

If the additives used in this process contain a SVHC-substance, then this will be specified in the corresponding Material Safety Data Sheet, section 15.

